PRINTED CIRCUIT BOARDS

INTERCONNECTION CARRIERS

State of the Art: PCB's	Revisio	Datum:	Seite:
PRINTED CIRCUIT BOARDS	01	4.11.2001	1/1

Schematic Key for Multilayer and HDI-Technology Build-Ups

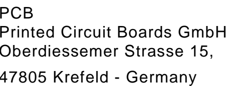
a	b	c	d	e	f	g + h+ i
06	183	FR4	35	L10.35_20.35	P18_10	S1

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

06_183_FR4_35_L10.35_20.35_P18_10_s1

Layers	in µ	Material	Build-Up	Assembly
Layer-1	35µ	Copper		B
	100µ	Prepreg	(100 µ PrePreg-Type: 2125)	B
	100µ	Prepreg		B
Layer-2	35µ	Copper		A1, B
	200µ	L-FR4		A1, B
	180µ	Prepreg	(180 µ PrePreg-Type: 7628)	B
	180µ	Prepreg		B
Layer-3	35µ	Copper		A2, B
	100µ	L-FR4		A2, B
Layer-4	35µ	Copper		A2, B
	180µ	Prepreg		B
	180µ	Prepreg		B
	200µ	L-FR4		A3, B
Layer-5	35µ	Copper		A3, B
	100µ	Prepreg		B
	100µ	Prepreg		B
Layer-99	35µ	Copper		B

© Copyright by Printed Circuit Boards GmbH


PCB
Printed Circuit Boards GmbH
Oberdiessemer Strasse 15,
47805 Krefeld - Germany

Fon: ++49 (0) 21 51 825 1
Fax: ++49 (0) 21 51 932 450
Web: http://www.p-c-b.de
eMail: info@p-c-b.de

Reg.-No.: KR HRB 2863
VAT-ID-No.: DE 120 157 078
Management:
Manfred Völker

Deutsche Bank Krefeld
BIC-(SWIFT)-Code: DEUTDEDD320
IBAN: DE18 3207 0080 0064 0318 00
IID: 320 700 80, BAN: 064 0318

DIN EN ISO
9001 : 2000
Certificate-No:
05124-1 / 2005